

On-Wafer Noise-Parameter Measurements at *W*-Band

Tauno Vähä-Heikkilä, *Student Member, IEEE*, Manu Lahdes, Mikko Kantanen, and Jussi Tuovinen, *Member, IEEE*

Abstract—A wide-band on-wafer noise-parameter measurement setup has been developed for *W*-band. The system is based on a cold-source method and uses a simple manual impedance tuner. In addition to noise parameters, *S*-parameters can be measured with the same setup. Using the developed system, noise parameters of an InP high electron-mobility transistor have been measured and results are shown in the 79–94-GHz frequency band. This is the first comprehensive report of noise-parameter measurements made on active devices at *W*-band.

Index Terms—High electron-mobility transistor (HEMT), noise measurement, noise parameter, on-wafer characterization.

I. INTRODUCTION

SEVERAL current and planned space missions for earth observation and astronomy applications require very low-noise receivers at *W*-band (75–110 GHz). A key component in this kind of low-noise receiver is a low-noise amplifier (LNA). The design of LNAs is greatly dependent on the availability of good noise models for devices used in the LNAs. Therefore, to design an optimum amplifier both noise and scattering (*S*)-parameters are needed. The noise parameters cannot be measured directly. The determination of the noise parameters involves scattering parameter and noise-figure measurements and data processing. The *S*-parameters of a two-port can be measured using a standard commercial vector network analyzer (VNA). However, the noise-parameter measurements are very challenging. Commercial measurement systems are available only up to 40 GHz. A good description of measurements below 40 GHz is given in [1]. Measured *W*-band noise parameters have been presented earlier only for passive devices and at a single frequency [5], [6]. We have recently been working with noise-parameter measurements at *V*- and *W*-bands. Our *V*-band (50–75 GHz) noise-parameter measurement setup and results were reported in [2]–[4] and the first results with an active device at *W*-band were published in [7]. This paper presents a full report on the measurement system that allows simultaneous on-wafer noise and scattering parameter measurements at *W*-band.

To determine the noise parameters, the noise figure of a device-under-test (DUT) is measured with different values of the

input reflection coefficients. The noise figure of a two-port as a function of source reflection coefficient Γ_i is given by [8]

$$F = F_{\min} + \frac{4r_n}{1 - |\Gamma_i|^2} \left| \frac{\Gamma_i - \Gamma_{\text{opt}}}{1 + \Gamma_{\text{opt}}} \right|^2 \quad (1)$$

where F_{\min} is the minimum noise figure of the two-port, r_n is the normalized noise resistance, and Γ_{opt} is the optimum reflection coefficient. Variables F_{\min} , r_n , and Γ_{opt} are called noise parameters. The noise parameters are obtained by fitting the above equation with the measured data.

II. MEASUREMENT SETUP

The measurement system is shown schematically in Fig. 1, and the photograph of the measurement setup is shown in Fig. 2, respectively. The measurement setup is based on the cold-source method [9], [10]. The improved technique, described in [2], is used. This technique corrects the effects of reflection-coefficient changes between the cold and hot states of the noise source and takes into account the losses of the passive network between the DUT and noise receiver.

The DUT is connected to the measurement system using waveguide probes. By including two waveguide switches, both noise and *S*-parameter measurements can be done without breaking any connections. These are commercial switches with less than 1-dB loss, more than 60-dB isolation between ports, and repeatability better than 0.05 at *W*-band. Only a simple uncalibrated one-port impedance tuner is needed in the input side of the DUT. This is possible due to switch 1. The one-port tuner consists of an adjustable waveguide short and attenuator. System characterization and the *S*-parameter measurements of the DUT are done using the HP8510C VNA. The VNA is also needed during noise measurements of the DUT to measure the reflection coefficient of the impedance tuner. The noise source is used here only during the calibration of the noise receiver. The noise-receiver calibration can also be done during long measurement sessions without breaking any connections due to switch 2. An LNA is used to increase the sensitivity of the noise receiver. The LNA was obtained through the Planck surveyor collaboration [11]. The mixer is used to downconvert the noise power from *W*-band to the measurement region of the HP8970A noise-figure meter. The local oscillator (LO) chain consists of the HP83650A synthesized sweeper, HP 8349B microwave amplifier, and HP83558A millimeter-wave source module. All measurement instruments are controlled using a personal computer (PC) via general-purpose interface

Manuscript received January 4, 2002; revised November 19, 2002. This work was supported by the European Space Agency/European Space Research and Technology Centre under Contract 1655/95/NL/MV and by the Graduate School in Electronics, Telecommunications, and Automation.

The authors are with Millimeter Wave Laboratory of Finland–Millilab, VTT TECHNICAL RESEARCH CENTRE OF FINLAND, Espoo, FIN-02044 VTT, Finland (e-mail: tauno.vaha-heikkila@vtt.fi; mikko.kantanen@vtt.fi).

Digital Object Identifier 10.1109/TMTT.2003.812554

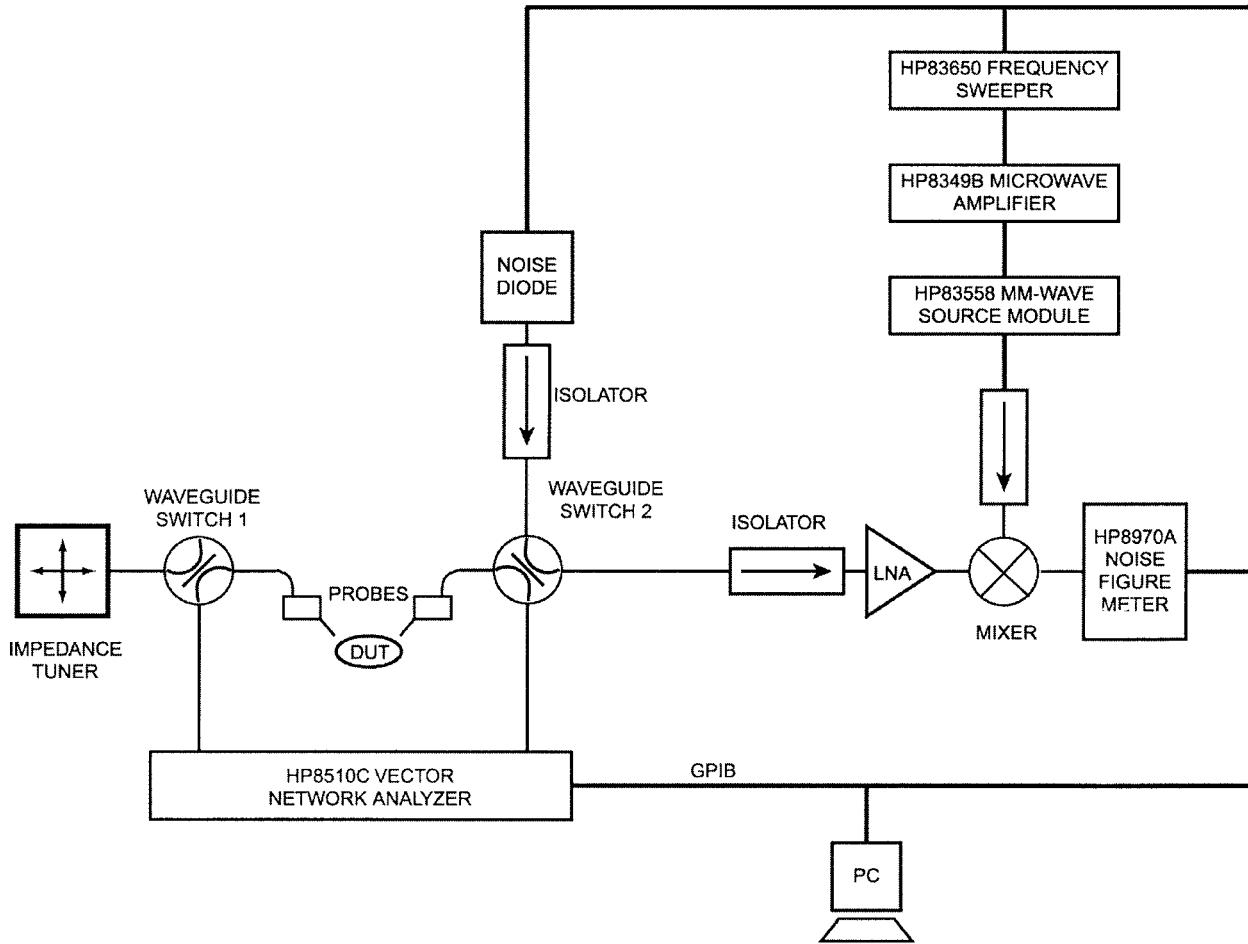


Fig. 1. Setup for noise-parameter measurements at 79–94 GHz.

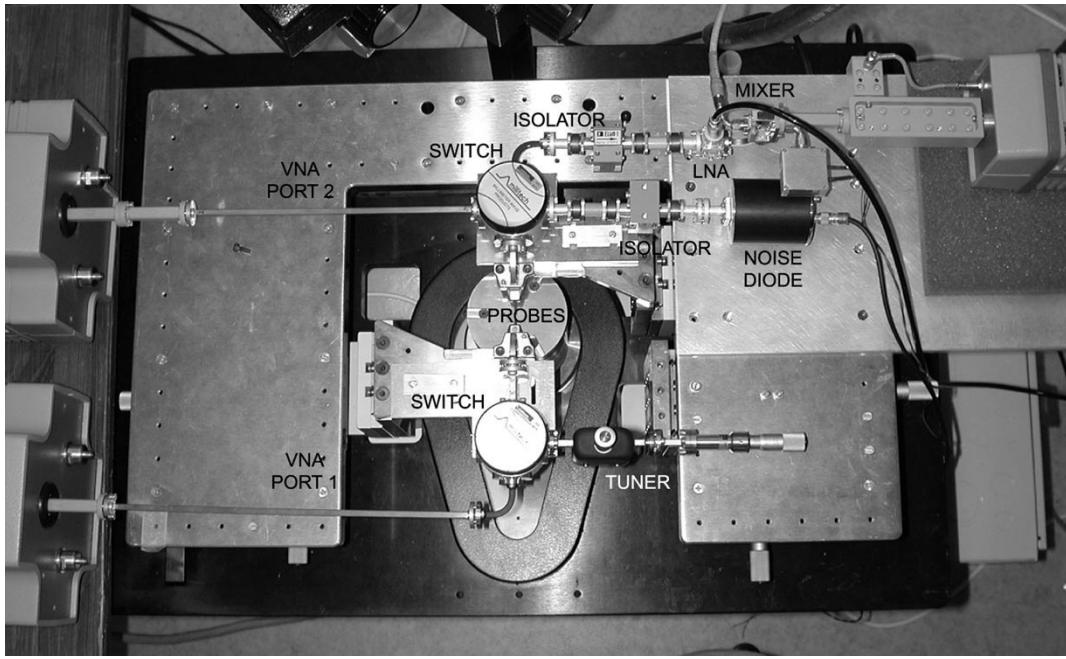


Fig. 2. Photograph of the measurement setup. All waveguide components are on top of a probe station.

bus (GPIB) line. The PC and in-house-made software make automatic data acquisition and complex calculations possible.

III. MEASUREMENTS

Measurements can be divided into the following three parts:

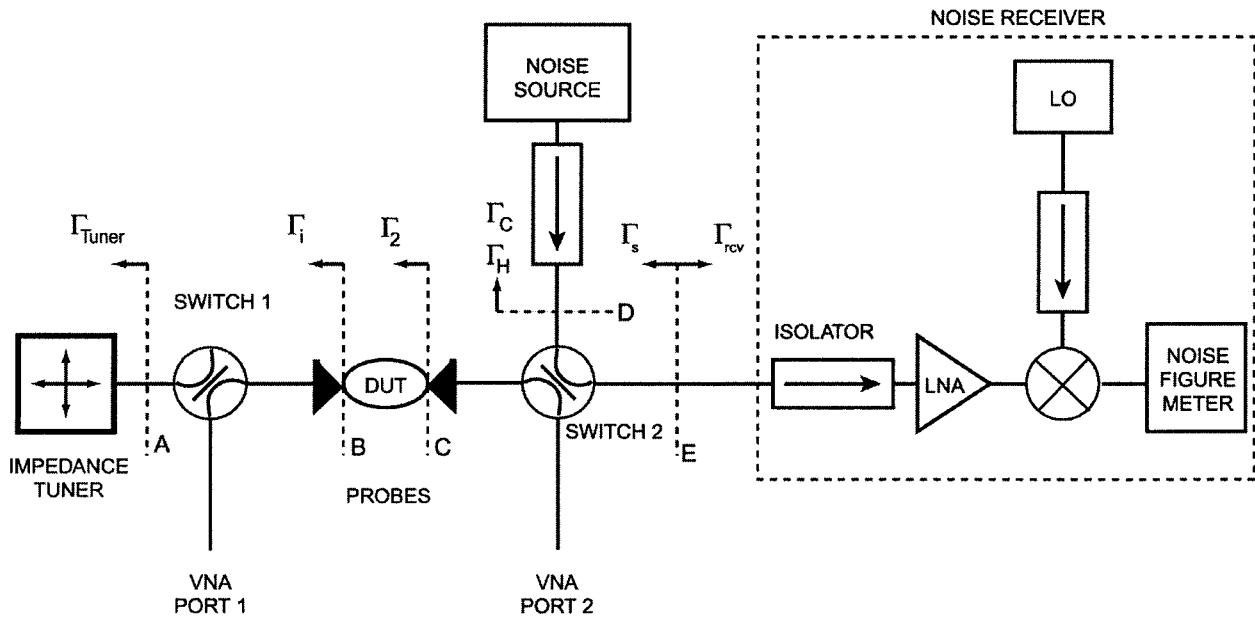


Fig. 3. Measurement system with reference planes and reflection coefficients.

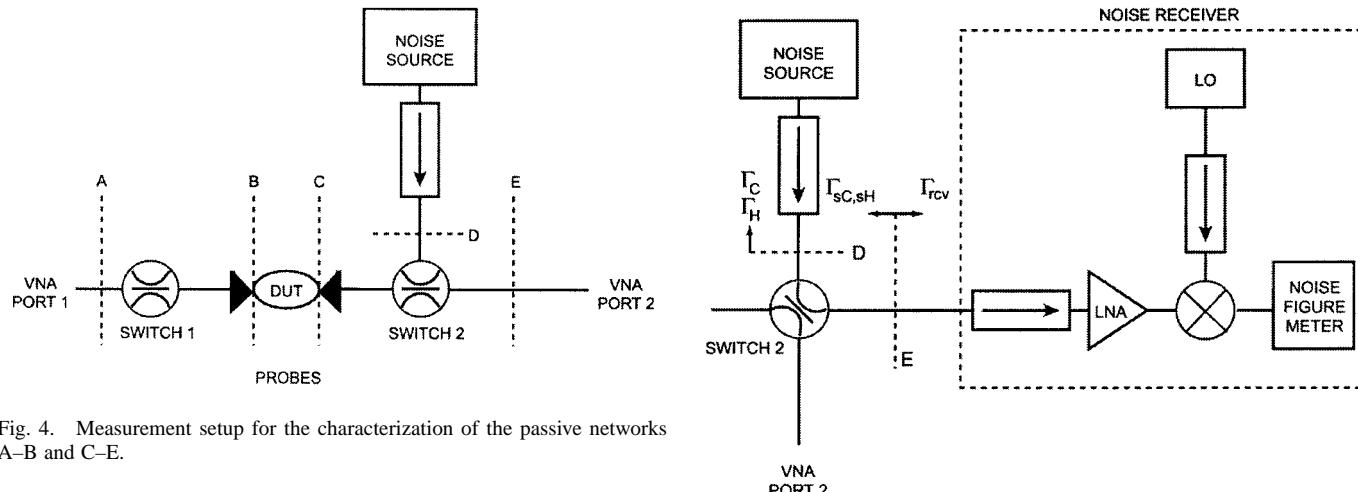


Fig. 4. Measurement setup for the characterization of the passive networks A–B and C–E.

- 1) system characterization;
- 2) noise-receiver calibration;
- 3) noise measurements of the DUT.

A. System Characterization

The system characterization is done using the VNA. It consists of the S -parameter measurements of the passive networks A–B, C–E, and D–E and the reflection-coefficient measurements of the noise receiver Γ_{rcv} and the noise source Γ_C , Γ_H (both cold and hot states). The meanings of these reference planes and reflection coefficients are shown in Fig. 3.

The passive networks A–B and C–E cannot be measured directly with the VNA because they are noninsertable. To characterize these networks, the VNA is first calibrated to the reference planes A and E using a one-port waveguide calibration. The configuration is shown in Fig. 4. An on-wafer two-port LRRM calibration [12] is then done to reference planes B and C. The S -parameters of these networks are calculated from the two sets of

Fig. 5. Measurement setup for the noise-receiver calibration.

error coefficients. The passive network D–E and reflection coefficients are also measured with the VNA. Measured attenuation of the passive network A–B was from 1.6 to 1.8 dB and attenuation of the passive network C–E was between 0.8–1.4 dB. Attenuation of passive network A–B limits impedance range of the impedance tuner. The maximum amplitude of achievable source reflection coefficient Γ_i is approximately 0.72 at 90 GHz at reference plane B.

B. Noise-Receiver Calibration

The noise-receiver calibration includes a determination of the kBG factor and the noise figure of the noise receiver. The noise source is connected to the noise receiver by switch 2. The noise power of the noise source is measured in the cold and hot states. This is done at all frequencies with the setup shown in Fig. 5. This figure also shows the notations of the reference planes D and E and reflection coefficients.

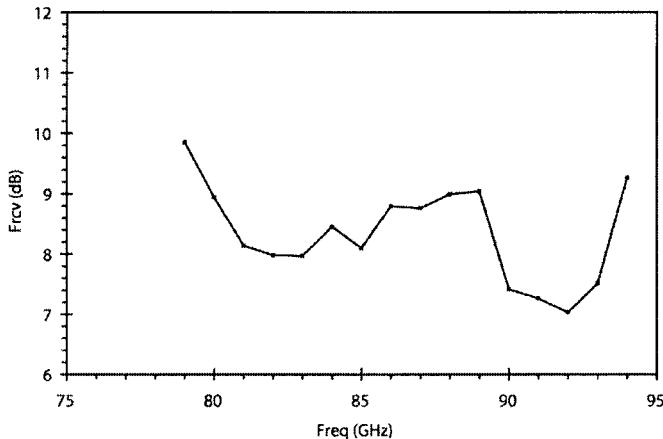


Fig. 6. Measured noise figure of the noise receiver.

The noise powers delivered to the noise receiver in the cold and hot states are calculated from

$$P_C = kBG T_{\text{Ceff}} \quad (2)$$

$$P_H = kBG T_{\text{Heff}} \quad (3)$$

where T_{Ceff} and T_{Heff} are the effective noise temperatures of the cold and hot states. Effective noise temperatures can be expressed in the form

$$T_{\text{Ceff}} = [T_C G_{aC} + (1 - G_{aC}) T_a] \cdot M_C \quad (4)$$

$$T_{\text{Heff}} = [T_H G_{aH} + (1 - G_{aH}) T_a] \cdot M_H \quad (5)$$

where T_a is the ambient temperature, T_C and T_H are the cold and hot noise temperatures of the noise source, G_{aC} and G_{aH} are the available gains of the passive network between the reference planes D and E in the cold and hot states, and M_C and M_H are the mismatch factors of the cold and hot states [13]

$$M_{C,H}(\Gamma_{sC,sH}) = \frac{(1 - |\Gamma_{sC,sH}|^2)(1 - |\Gamma_{\text{rcv}}|^2)}{|1 - \Gamma_{sC,sH}\Gamma_{\text{rcv}}|^2}. \quad (6)$$

The kBG factor is

$$kBG = \frac{P_{Hm} - P_{Cm}}{T_{\text{Heff}} - T_{\text{Ceff}}} \quad (7)$$

where P_{Hm} and P_{Cm} are the measured noise powers in the hot and cold states.

When a noise diode is used as a noise source, then $T_C = T_a$ and (4) reduces to

$$T_{\text{Ceff}} = T_a M_C. \quad (8)$$

The noise factor of the noise receiver F_{rcv} , which is independent of the source reflection coefficient Γ_i , can be expressed in the form

$$F_{\text{rcv}} = \frac{T_{\text{Heff}} - Y \cdot T_{\text{Ceff}}}{T_0(Y - 1)} + 1 \quad (9)$$

where T_0 is the standard temperature, and the Y coefficient is

$$Y = \frac{P_{Hm}}{P_{Cm}}. \quad (10)$$

The measured noise figure of the noise receiver is presented as a function of frequency in Fig. 6.

C. Noise Measurements of the DUT

After system characterization and noise-receiver calibration, the noise measurements of the DUT are carried out. The VNA is calibrated to the reference planes B and C using the line-reflect-reflect-match (LRRM) on-wafer calibration. The DUT is then placed between the probes and set to the operating point of interest. The S -parameters of the DUT are measured. Noise-figure measurements are done in two steps. The first step is to measure the reflection coefficient of the impedance tuner Γ_{tuner} using the VNA, and the second step is to measure the corresponding noise power of the entire system. The VNA port 1 is switched to the tuner. The tuner is set and its reflection coefficient Γ_{tuner} is measured. The tuner is then switched to the DUT and the corresponding noise power P_i is measured with the noise receiver. These steps are done for every selected value of the tuner and as a function of the frequency. Since the S -parameters of the passive network A-B are known, the source reflection coefficient Γ_i can be calculated. It is then possible to calculate the noise figure of the entire system as a function of the source reflection coefficient Γ_i [2]

$$F_{\text{tot},i} = \frac{P_i |1 - S_{11\text{DUT}}\Gamma_i|^2 |1 - \Gamma_s\Gamma_{\text{rcv}}|^2 |1 - S_{11\text{CE}}\Gamma_2|^2}{T_0 kBG |S_{21\text{DUT}}|^2 (1 - |\Gamma_i|^2) |S_{21\text{CE}}|^2} - \frac{T_a}{T_0} + 1 \quad (11)$$

where $S_{11\text{DUT}}$ and $S_{21\text{DUT}}$ are the S -parameters of the DUT and $S_{11\text{CE}}$ and $S_{21\text{CE}}$ are the S -parameters of the passive network between reference planes C and E, respectively.

The noise figure of the DUT as a function of the source reflection coefficient $F_{\text{DUT}}(\Gamma_i)$ is calculated using the Friis formula [14]

$$F_{\text{DUT}}(\Gamma_i) = F_{\text{tot}} - \frac{F_{\text{rcv}}(\Gamma_i) - G_{a\text{CE}}}{G_{a\text{DUT}}G_{a\text{CE}}} \quad (12)$$

where $G_{a\text{DUT}}$ and $G_{a\text{CE}}$ are the available gain of the DUT and network between reference planes C and E, $F_{\text{rcv}}(\Gamma_i)$ is the noise figure of the noise receiver that is dependent of source reflection coefficient Γ_i

$$F_{\text{rcv}}(\Gamma_i) = F_{\text{rcv}} \cdot \frac{|1 - \Gamma_{\text{rcv}}\Gamma_s|^2}{1 - |\Gamma_s|^2} \quad (13)$$

where Γ_s is the reflection coefficient seen by the noise receiver. After solving F_{DUT} and Γ_i data pairs, noise parameters can be extracted with mathematical fitting methods.

IV. RESULTS

As an example of W -band noise-parameter measurements, a DaimlerChrysler InP high electron-mobility transistor (HEMT) was measured. It has $0.18\text{-}\mu\text{m}$ gate length and $2 \times 40\text{ }\mu\text{m}$ gatewidth. During the measurements, the HEMT was set to the operating point with a drain voltage $V_{\text{ds}} = 1.0\text{ V}$ and a drain current $I_{\text{ds}} = 10\text{ mA}$. The noise parameters of the HEMT are shown in Figs. 7–10. To show repeatability, three different measurements are presented ($M1$ – $M3$ in Figs. 7–10). The noise parameters are extracted from measurement data using Lane's method [15]. Five different source impedances were used. One

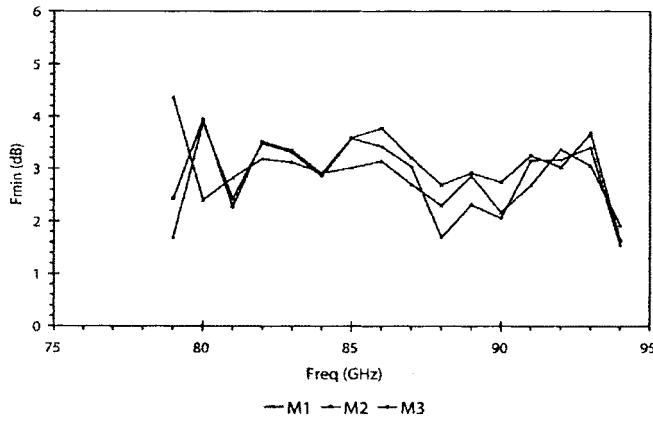


Fig. 7. Measured minimum noise figure as a function of frequency. Measurements were carried out three times.

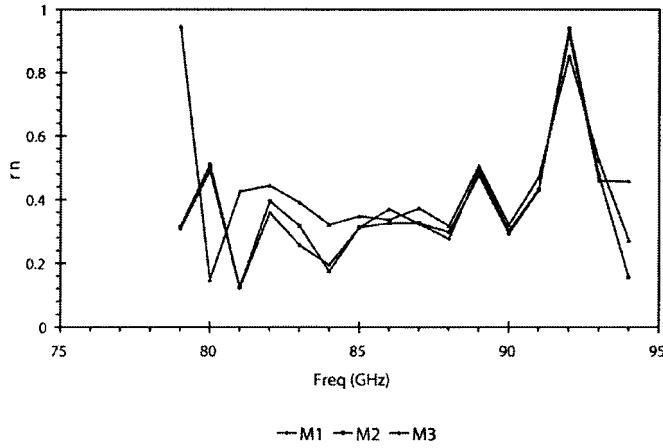


Fig. 8. Normalized noise resistance as a function of frequency. Measurements were carried out three times.

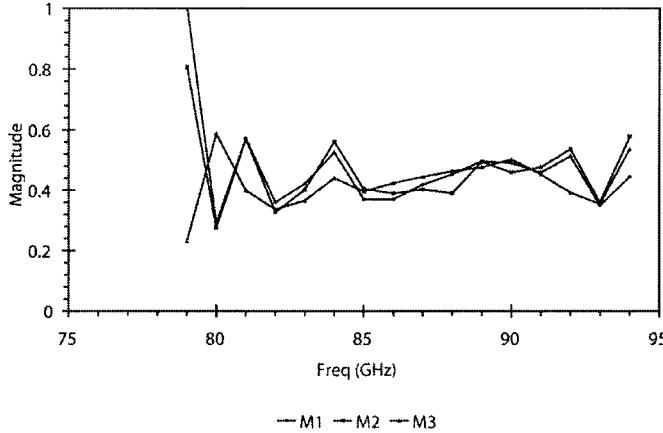


Fig. 9. Magnitude of the optimum reflection coefficients. Measurements were carried out three times.

was set close to the center of the Smith chart and the others were set symmetrically around the center of the Smith chart. These are presented in Fig. 11 at 90 GHz. Noise parameters of similar HEMTs were presented in [4] at the *V*-band. *V*-band measurements were made on a different device from the same wafer. Peaks are seen in the normalized noise resistance and the phase of Γ_{opt} around 89–92 GHz. These are likely due to

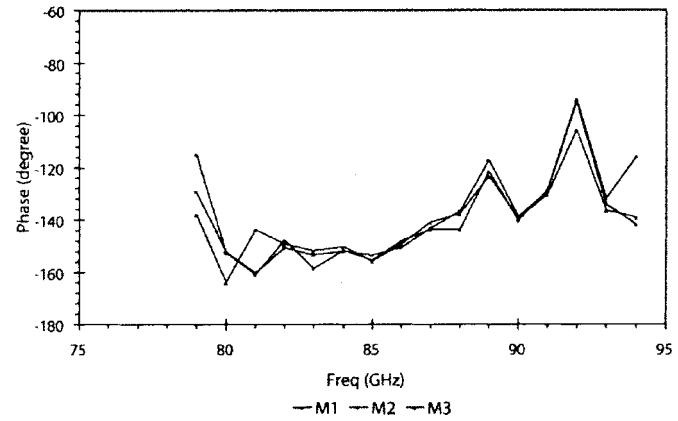


Fig. 10. Phase of the optimum reflection coefficients. Measurements were carried out three times.

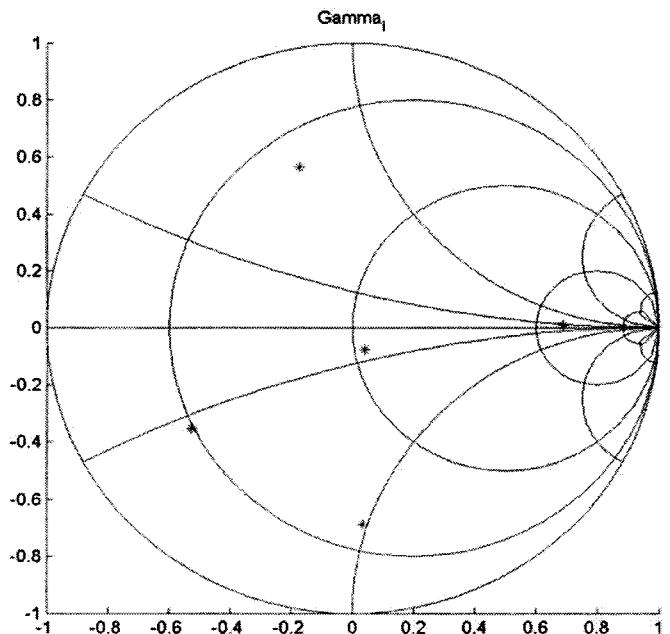


Fig. 11. Source reflection coefficients Γ_i at 90 GHz in measurement 2.

the difficulties in the on-wafer calibrations and the sensitivity of the noise receiver at these frequencies.

V. DISCUSSION AND ERROR ANALYSIS

Sensitivity and linearity of the noise receiver are important in noise-parameter measurements. The noise power P_i as a function of frequency is shown in Fig. 12. The source reflection coefficient Γ_i is the nearest value of the center of the Smith chart (see Fig. 11). The noise power is under 400 K below 88 GHz and increases rapidly toward higher frequencies reaching 13 600 K at 93 GHz. This is one possible explanation for the peaks in the normalized noise resistance and the phase of Γ_{opt} . The measurement system will be improved by obtaining a *W*-band LNA for the noise receiver with lower noise figure, higher gain, and wider bandwidth.

As can be seen from the measurement results, single-frequency measurements are not reliable at the *W*-band. Wide-band measurements are important for obtaining reliable

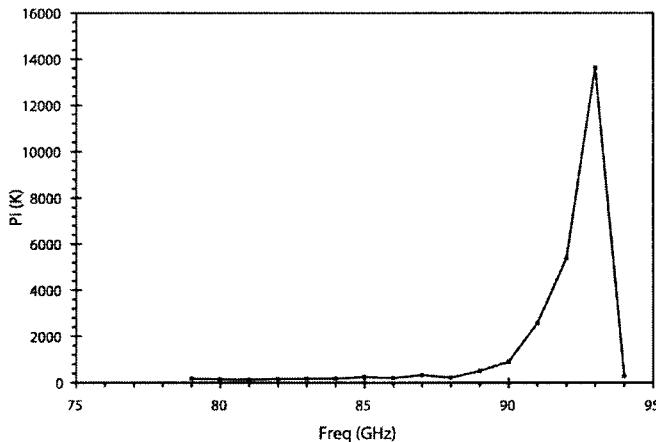


Fig. 12. Noise power P_i as a function of frequency. The corresponding source reflection coefficient Γ_i is the point closest to the center of the Smith chart.

results. All steps are critical in the noise-parameter measurements with characterization of the passive networks A–B and C–E needing careful attention. These include both waveguide and on-wafer calibrations. If system characterization is not done carefully, large systematic errors may remain undiscovered. These errors are usually caused by reflections in the setup, which are difficult to calibrate out.

Since there are no active on-wafer noise-parameter standards, which could be used directly to determine the uncertainty of the measurement system, the uncertainties have to be determined indirectly. The task is quite complex since the noise-parameter measurements involve a large number of variables and numerous different measurement steps and calibrations. Approximately 40 measured variables are used to calculate the noise parameters. Measurements consist of S -parameters and reflection coefficients (both magnitudes and phases), noise power measurements, and the excess noise ratio (ENR) calibration of the noise source.

A partial derivative method is usually used in uncertainty analysis, but when the number of variables is large or variables have complicated functional relations, it becomes impractical [16]. Instead, a statistical Monte Carlo method is applied in the analysis of the uncertainties of noise parameters [17]. In the Monte Carlo method, a large set of noise parameters are created by adding random fluctuations to the measured data. When the number of conducted runs is large (thousands), results can be studied statistically. Graphical presentation of the Monte Carlo method is shown in Fig. 13. Uncertainties with random distribution are added to measured values, and noise parameters are calculated. This is repeated many times and the new calculated noise parameters are stored after every run. Having many sets of noise parameters, results can be analyzed statistically.

Monte Carlo simulations were done at a single frequency. Uncertainties, presented in Table I, were used for each measured variable, and noise parameters were calculated. Uncertainties are divided in classes A and B [18]. The evaluation of type-A uncertainty was done by statistical method and type B was evaluated by other means, e.g., using approximation or manufacturer's specifications. Evaluation of uncertainty values of measured values is based mostly on [17], where similar work was

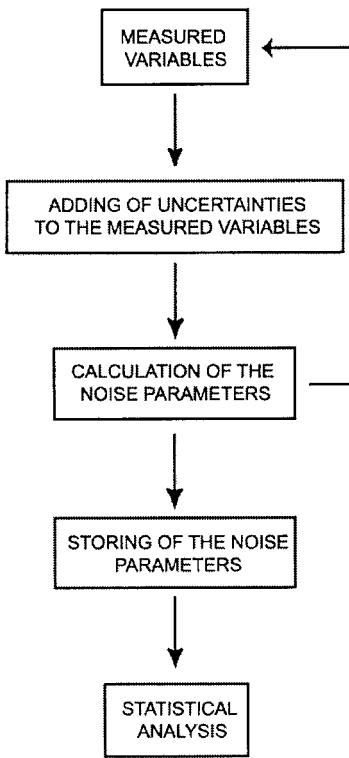


Fig. 13. Graphical presentation of Monte Carlo analysis used to analyze uncertainties of the noise parameters.

TABLE I
UNCERTAINTIES FOR MEASURED PARAMETERS

Measured parameter	Uncertainty	Type
$\Gamma_{\text{tuner}}, \Gamma_{\text{rev}}, \Gamma_H, \Gamma_C$	0.005	B
S_{11_AB}, S_{11_CE}	0.036	A, B
S_{22_AB}, S_{22_CE}	0.036	A, B
$S_{12_AB}, S_{21_AB}, S_{12_CE} \times S_{21_CE}$	0.0013	A, B
S_{11_DE}, S_{22_DE}	0.005	B
S_{12_DE}, S_{21_DE}	0.006	B
S_{11_DUT}	0.036	A
S_{12_DUT}, S_{21_DUT}	0.05	A
S_{22_DUT}	0.024	A
ENR [dB]	0.1	B
$P_H, P_C, P_i [K]$	1.01	A
$T_a [K]$	1	A

TABLE II
RESULTS OF MONTE CARLO SIMULATIONS AT 90 GHz

Parameter	Mean	2σ
$F_{\text{min}} [\text{dB}]$	2.8	± 0.7
r_n	0.3	± 0.09
$ \Gamma_{\text{opt}} $	0.46	± 0.09
ϕ_{opt}	-139	± 10

carried out for V -band cold-source noise-parameter setup. For the uncertainties of S -parameters, the magnitude is determined using a rectangular distribution and corresponding angle using a uniform distribution from -180° to 180° . Calculated Monte Carlo simulation results for measurement 2 at 90 GHz are presented in Table II. The mean of each noise parameter and 2σ (95.5% confidence level) of 10 000 simulation runs are shown in this table.

VI. CONCLUSION

A *W*-band on-wafer noise-parameter measurement system has been designed and built. For the first time, to the author's knowledge, wide-band results for the *W*-band on-wafer noise parameters of an active device have been reported. The noise parameters of an InP HEMT (DaimlerChrysler $2 \times 40 \mu\text{m}$) were measured using the cold-source method. Measurement results were presented between the 79–94-GHz frequency band.

ACKNOWLEDGMENT

The help of T. Gaier, Jet Propulsion Laboratory, Pasadena, CA, and N. Hughes and P. Kangaslahti, both of Ylinen Electronics, Kauniainen, Finland, are greatly appreciated. The authors would also like recognize the invaluable comments and contribution of T. Närhi, European Space Agency (ESA), Noordwijk, The Netherlands, as well as colleagues T. Karttaavi, J. Varis, H. Hakojärvi and M. Jenu, all of the Millimeter Wave Laboratory of Finland–Millilab, VTT TECHNICAL RESEARCH CENTRE OF FINLAND, Espoo, Finland.

REFERENCES

- [1] J. Laskar, M. R. Murti, S. Y. Yoo, E. Gebara, and H. M. Harris, "Development of complete on-wafer cryogenic characterization: *S*-parameters, noise-parameters and load-pull," in *Eur. GaAs and Related III-V Compounds, Application Symp. Dig.*, Amsterdam, The Netherlands, 1998, pp. 33–38.
- [2] M. Lahdes, M. Sipilä, and J. Tuovinen, "60 GHz noise parameter measurements using cold-source method," in *49th ARFTG Conf. Dig.*, Denver, CO, 1997, pp. 146–154.
- [3] M. Lahdes and J. Tuovinen, "*V*-band on-wafer noise parameter measurements," in *Eur. GaAs and Related III-V Compounds, Application Symp. Dig.*, Amsterdam, The Netherlands, 1998, pp. 39–44.
- [4] M. Kantanen, M. Lahdes, J. Tuovinen, T. Vähä-Heikkilä, P. Kangaslahti, P. Jukkala, and N. Hughes, "A wideband automated measurement system for on-wafer noise parameter measurements at 50–75 GHz," in *Eur. GaAs and Related III-V Compounds, Application Symp. Dig.*, 2001, pp. 255–258.
- [5] T. A. Alam, R. D. Pollard, and C. M. Snowden, "Determination of *W*-band noise parameters," *Electron. Lett.*, vol. 34, no. 3, pp. 288–289, 1998.
- [6] ———, "The determination of on-wafer noise parameters at *W*-band," in *Proc. 27th Eur. Microwave Conf.*, Jerusalem, Israel, 1997, pp. 687–691.
- [7] T. Vähä-Heikkilä, M. Lahdes, J. Tuovinen, M. Kantanen, P. Kangaslahti, P. Jukkala, and N. Hughes, "*W*-band on-wafer noise parameter measurements," in *Proc. 31st Eur. Microwave Conf.*, London, U.K., 2001, pp. 355–358.
- [8] IRE Subcommittee on Noise, "Representation of noise in linear two-ports," *Proc. IRE*, vol. 48, pp. 69–74, Jan. 1960.
- [9] V. Adamian and A. Uhlir, "A novel procedure for receiver noise characterization," *IEEE Trans. Instrum. Meas.*, vol. IM-22, pp. 181–182, 1973.
- [10] R. Meierer and C. Tsironis, "An on-wafer noise parameter measurement technique with automatic receiver calibration," *Microwave J.*, vol. 38, no. 3, pp. 80–88, 1995.
- [11] J. Tuovinen, P. Kangaslahti, P. Haapanen, N. Hughes, P. Jukkala, T. Karttaavi, O. Koistinen, M. Lahdes, H. Salminen, J. Tanskanen, and S. Urpo, "Development of 70 GHz receivers for the Planck LFI," *Astrophys. Lett. Commun.*, vol. 37, pp. 181–187, 2000.
- [12] A. Davidson, K. Jones, and E. Strid, "LRM and LRRM calibrations with automatic determination of load inductance," in *36th ARFTG Conf. Dig.*, Monterey, CA, 1990, pp. 57–62.

- [13] E. Strid, "Noise measurements for low-noise GaAs FET amplifiers," *Microwave Syst. News*, vol. 10, pp. 62–70, 1981.
- [14] H. T. Friis, "Noise figures of radio receivers," *Proc. IEEE*, vol. 57, pp. 1461–1462, Aug. 1969.
- [15] R. Q. Lane, "The determination of device noise parameters," *Proc. IEEE*, vol. 57, pp. 1461–1462, Aug. 1962.
- [16] V. Adamian, "Calibration, measurement and accuracy of the noise parameter measurements," in *IEEE MTT-S Int. Microwave Symp. Workshop*, San Francisco, CA, 1996, pp. 83–110.
- [17] M. Lahdes, "Uncertainty analysis of *V*-band on-wafer noise parameter measurement system," in *28th Eur. Microwave Conf.*, Amsterdam, The Netherlands, 1998, pp. 445–450.
- [18] B. N. Taylor and C. E. Kuyatt, "Guidelines for evaluating and expressing the uncertainty on NIST measurement results," NIST, Boulder, CO, Tech. Note 1297, 1994.



Tauno Vähä-Heikkilä (S'01) received the B.S. and M.S. degrees in physics from the University of Turku, Turku, Finland, in 2000 and 2001, respectively. His M.S. thesis concerned *W*-band on-wafer noise-parameter measurements.

He was a Trainee Research Scientist and, since 2001, he has been a Research Scientist with the Millimeter Wave Laboratory of Finland–Millilab, VTT TECHNICAL RESEARCH CENTRE OF FINLAND, Espoo, Finland. He is also currently a Visiting Scholar with the Radiation Laboratory, The University of Michigan at Ann Arbor. His research interests include RF microelectromechanical systems (MEMS) and millimeter-wave on-wafer measurements.

Mr. Vähä-Heikkilä has been a secretary for the IEEE Antennas and Propagation (AP)/Electron Devices (ED)/Microwave Theory and Techniques (MTT) Finland Chapter since 2001.



Manu Lahdes received the Master of Science degree in electrical engineering degree from the Helsinki University of Technology, Espoo, Finland, in 1996.

Since 1996, he has been with a Research Scientist the Millimeter Wave Laboratory of Finland–Millilab, VTT TECHNICAL RESEARCH CENTRE OF FINLAND, Espoo, Finland. His research interests in the millimeter-wave area have been on-wafer noise-parameter measurements, cryogenic on-wafer measurements, active device modeling, and MMIC design and testing. He has several papers. His current activities also include passive millimeter imaging.



Mikko Kantanen received the Master of Science degree in electrical engineering degree from the Helsinki University of Technology (HUT), Espoo, Finland, in 2001.

Since 1999, he has been with the Millimeter Wave Laboratory of Finland–Millilab, VTT TECHNICAL RESEARCH CENTRE OF FINLAND, Espoo, Finland, initially as a Trainee Research Scientist and, since 2001, as a Research Scientist involved with noise measurements at millimeter waves. He is also currently involved with other millimeter-wave activities including on-wafer measurement systems, monolithic microwave integrated circuit (MMIC) design, and passive imaging.



Jussi Tuovinen (S'86-M'91) received the Dipl.Eng., Lic.Tech., and Dr.Tech. degrees in electrical engineering from the Helsinki University of Technology (HUT), Espoo, Finland, in 1986, 1989, and 1991, respectively.

From 1986 to 1991, he was a Research Engineer with the HUT Radio Laboratory, where he was involved with millimeter-wave antenna testing for the European Space Agency (ESA), quasi-optical measurements, and Gaussian beam theory. From 1991 to 1994, he was a Senior Post-Doctoral Fellow with the Five College Radio Astronomy Observatory, University of Massachusetts, Amherst, where he studied holographic testing methods and developed frequency multipliers up to 1 THz. From 1994 to 1995, he was a Project Manager with the HUT Radio Laboratory, where he was involved with hologram compact antenna test range (CATR) and 119-GHz receiver development for *Odin*-satellite. He is currently a co-investigator and heads development of 70-GHz receivers for the low-frequency instrument of the ESA Planck Surveyor. His research activities also includes development of methods for on-wafer testing of integrated circuits and components. He is currently a Research Professor with VTT TECHNICAL RESEARCH CENTRE OF FINLAND Information Technology and a Director of the Millimeter Wave Laboratory of Finland-MilliLab, ESA External Laboratory. From 2001 to 2002, he was a Visiting Researcher with the University of Hawaii at Manoa, where he developed communications methods using retrodirective antennas. He has authored or coauthored over 100 papers.

Dr. Tuovinen is a past secretary of the Finnish National Committee of the Committee on Space Research (COSPAR) and the IEEE Finland Section. He was also the executive secretary of the Local Organizing Committee of the 27th Plenary Meeting of COSPAR, held in 1988. In 1998, he was a co-chairman of the Second ESA Workshop on Millimeter Wave Technology and Applications. He has served as a chairman of the IEEE Microwave Theory and Techniques (MTT)/Antennas and Propagation (AP) Finland Chapter. He is the chairman of the Third ESA Workshop on Millimeter Wave Technology and Applications. He was the recipient of an ESA Fellowship for multiplier work at the University of Massachusetts in 1992 and again in 1993.